

REMARKS

The Examiner has objected to the specification. The specification has been amended to use the correct numeral (14) for identification of the test head.

The Examiner has objected to claim 7. The correct term "male" has been substituted for the incorrect "mail".

The Examiner has objected to the IDS as having three published U.S. applications located in the incorrect section. Applicant is willing to place the references in any section the Examiner desires, but in a recent call to the USPTO "Inventors Assistance Center", the undersigned was told that the U.S. Patent Documents section was the correct place for published applications.

The Examiner has rejected the claims as being unpatentable over Botka et al. in view of Phillips.

Botka et al. shows a blind mate connector for an electronic circuit tester. As the Examiner has noted, the patent does not show or suggest the use of a de-mating device attached to one of said probe card and said test head for urging said test head and said probe card apart by applying a separating force therebetween.

Phillips shows a docking apparatus for a semiconductor wafer prober. The Examiner cites this patent as providing a de-mating device. Other than a conclusory statement that it would be obvious to combine the teachings of Botka et al. with Phillips, the Examiner cites no teaching, suggestion or motivation to do so from within the cited patents.

In addition, it is respectfully submitted that Phillips does not provide the teaching suggested by the Examiner. The springs 64 serve to provide pressure to squeeze the fuzz buttons 72 between the load board 76 and the interface board 70. Col. 3,

lines 25-40 (80 and 82 are merely an alignment pin and socket, and 56 laterally biases the sleeve 29 toward the wall portion 54). It needs to be noted that even if the head is retracted enough to remove any applied pressure on the springs 64, the fuzz buttons may still be in contact, hence there is no de-mating.

Also, because of the use of fuzz buttons in Phillips, there is no mating friction as found in coaxial connectors and no reason to provide a de-mating device. The springs of Phillips are for providing good connections instead of disconnection.

Neither of the above-cited references teaches nor suggest a de-mating device as included in the instant claims. Therefore, it is respectfully submitted that the claims are patentable over Botka et al. in view of Phillips.

In view of the foregoing amendments and remarks, it is respectfully submitted that the application is in condition for allowance and notification of same is requested.

If any fees are required by this communication which are not covered by an enclosed check, please charge such fees to our Deposit Account No. 16-0820, Order No. 34896.

Respectfully submitted,

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